



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-16
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

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Legal statement
Supplier acceptance* true Legal declaration* Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
SMA6T36AY	AHSR*UAY036D	A	ZA41	2025-04-16
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	71.00	mg	Each	ECOPACK® 2
<b>Identity</b>	<b>Authority</b>			
Comment	0			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
soj	4.3x2.8	2	gull wing
Comment			
Comment	SR SMA		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 3rd January 2025			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.013	alloy	183
Lead	0.817	solder	11507

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
X	O	O	O	O	

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead (Pb)	1000 ppm	0.82	Soft solder	11507
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Lead dinitrate	1000 ppm	0.817	Soft solder	925255



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	<b>Gold, Tin,</b>

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	AHSR*UAY036D			71.0000		5999997.0	999999.0
note : Substance present with less 0.001mg will not be declared in this document													
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	1.690	mg	supplier	die	Silicon(Si)	7440-21-3		1.625	mg	961538	22887	
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.018	mg	10651	254	
				supplier	metallisation	Gold(Au)	7440-57-5		0.009	mg	5325	127	
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.013	mg	7692	183	
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.002	mg	1183	28	
				supplier	passivation	Silicon oxide	7631-86-9		0.009	mg	5325	127	
				supplier	polymer coating	polyimide	proprietary		0.014	mg	8284	197	
Leadframe	M-004 Copper and its alloys	20.400	mg	supplier	alloy	Cu	7440-50-8		20.390	mg	999510	287183	
				supplier	alloy	Zn	7440-66-6		0.001	mg	49	14	
				supplier	alloy	Fe	7439-89-6		0.002	mg	98	28	
				supplier	alloy	P	7723-14-0		0.007	mg	343	99	
Soft solder	Solder	0.883	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	0.817	mg	925255	11507	
				supplier	solder	Tin(Sn)	7440-31-5		0.044	mg	49830	620	
				supplier	solder	Silver(Ag)	7440-22-4		0.022	mg	24915	310	
Encapsulation	M-011 Other inorganic materials	41.186	mg	supplier	mold compound	Amorphous silic	60676-86-0		30.501	mg	740567	429592	
				supplier	mold compound	quartz	14808-60-7		0.419	mg	10173	5901	
				supplier	mold compound	Epoxy Cresol N	29690-82-2		6.285	mg	152600	88521	
				supplier	mold compound	Phenol resin	9003-35-4		3.352	mg	81387	47211	
				supplier	mold compound	metal hydroxide	proprietary		0.419	mg	10173	5901	
				supplier	mold compound	phosphorus cor	proprietary		0.042	mg	1020	592	
				supplier	mold compound	Carbon black	1333-86-4		0.168	mg	4079	2366	
Connections coating	Solder	0.641	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		0.641	mg	1000000	9028	
Clip		6.200	mg	supplier	alloy	Cu	7440-50-8		6.197	mg	999500	87280	
				supplier	alloy	Zn	7440-66-6		0.0002	mg	40	3	
				supplier	alloy	Fe	7439-89-6		0.0006	mg	100	9	
				supplier	alloy	P	7723-14-0		0.002	mg	360	31	